

PATENT ASSIGNMENT

SUBMISSION TYPE: NEW ASSIGNMENT

APPLICATION NUMBER
10/249369

NATURE OF CONVEYANCE: ASSIGNMENT OF ASSIGNOR'S INTEREST

CONVEYING PARTY DATA

Name: Chen, Kun-Ching

Execution Date: 08/22/2002

Name: Tong, Ho-Ming

Execution Date: 08/14/2002

Name: Lee, Chun-Chi

Execution Date: 08/14/2002

RECEIVING PARTY DATA

Name: Advanced Semiconductor Engineering, Inc.

Street Address: 26, Chin 3rd Rd., Nantze Export Processing Zone

Internal Address:

City: Kaohsiung

State:

Country: TAIWAN

Postal Code: 811

The USPTO, Office of Public Records, will send correspondence via facsimile to **FAX NUMBER:** 886-2-2369-7233

CORRESPONDENCE DATA:

Correspondence will be sent via US Mail when a fax number has not been provided or the fax attempt is unsuccessful.

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CUSTOMER NUMBER: 031561

NAME OF PERSON SIGNING: Belinda Lee

DATE SIGNED: 04/03/2003

Total Attachments: 2

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PATENT
REEL: 013535 FRAME: 0200

OP \$40.00 10249369

ASSIGNMENT

WHEREAS,

1. Kun-Ching Chen
2. Ho-Ming Tong
3. Chun-Chi Lee

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **FLIP CHIP PACKAGE SUBSTRATE**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Advanced Semiconductor Engineering, Inc.
of 26, Chin 3rd. Rd., 811, Nantze Export Processing Zone, Kaohsiung, Taiwan,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Kun-Ching Chen
Signature:

8/22/02
Date:

Sole or First Joint Inventor: Kun-Ching Chen

Ho-Ming Tong
Signature:

8/14/02
Date:

Second Joint Inventor(if any): Ho-Ming Tong

Chun-Chi Lee
Signature:

8/14/02
Date:

Third Joint Inventor(if any): Chun-Chi Lee